

■ FEATURES

- UL recognition, file #E230084
- Glass passivated chip junction
- Thin single in-line package
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

■ TYPICAL APPLICATIONS

General purpose use in AC/DC bridge full wave rectification for switching power supply, home appliances, office equipment, industrial automation applications.

■ MECHANICAL DATA

- **Package:** 6KBJ
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked on body

■ MAXIMUM RATINGS (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GBJ1508A	
Device marking code			GBJ1508A	
Maximum Repetitive Peak Reverse Voltage	VRRM	V	800	
Maximum RMS Voltage	VRMS	V	560	
Maximum DC blocking Voltage	VDC	V	800	
Average rectified output current @60Hz sine wave, R-load	With heatsink T _c =110°C	I _O	A	15.0
	Without heatsink T _a =25°C			3.5
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, T _j =25°C	IFSM	A	420	
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, T _j =25°C			840	
Current squared time @1ms≤t≤8.3ms T _j =25°C, Rating of per diode	I ² t	A ² s	732	
Storage temperature	T _{stg}	°C	-55 ~ +150	
Junction temperature	T _j	°C	-55 ~ +150	
Dielectric strength @ Terminals to case, AC 1 minute	V _{dis}	KV	2.5	
Mounting torque @Recommend torque: 5kg·cm	Tor	kg·cm	8	

■ ELECTRICAL CHARACTERISTICS (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GBJ1508A
Maximum instantaneous forward voltage drop per diode	V _F	V	I _{FM} =7.5A	0.92
Maximum DC reverse current at rated DC blocking voltage per diode	I _R	μA	T _j =25°C	5
			T _j =125°C	200
Typical junction capacitance	C _j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	275

■ **THERMAL CHARACTERISTICS** ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

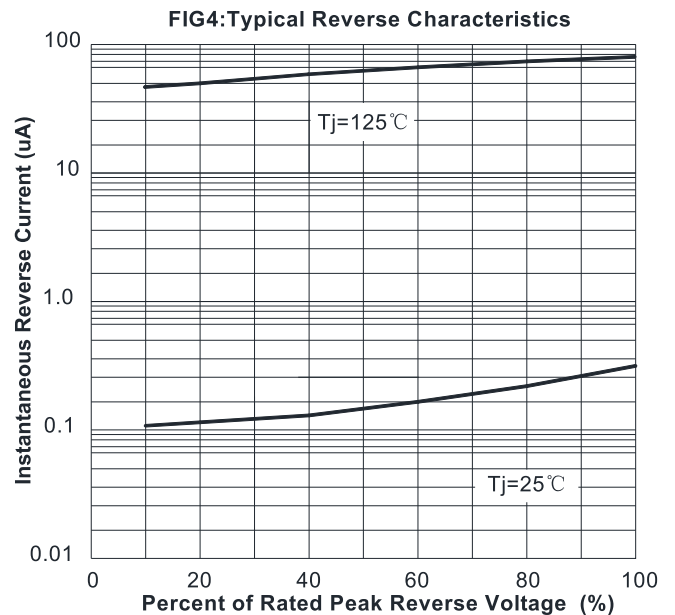
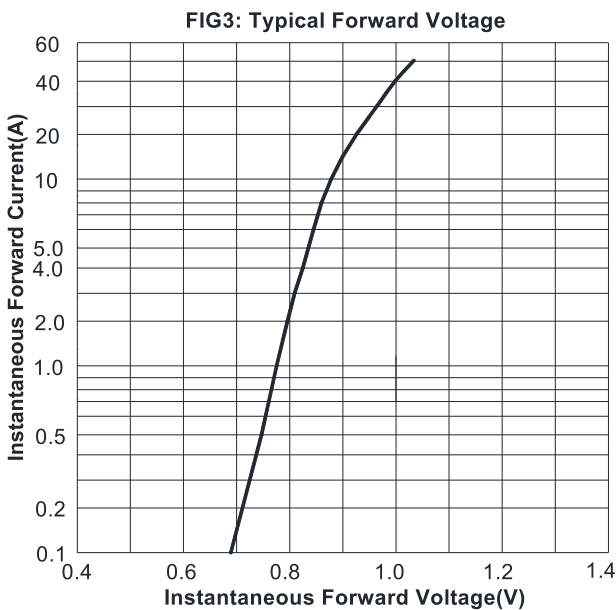
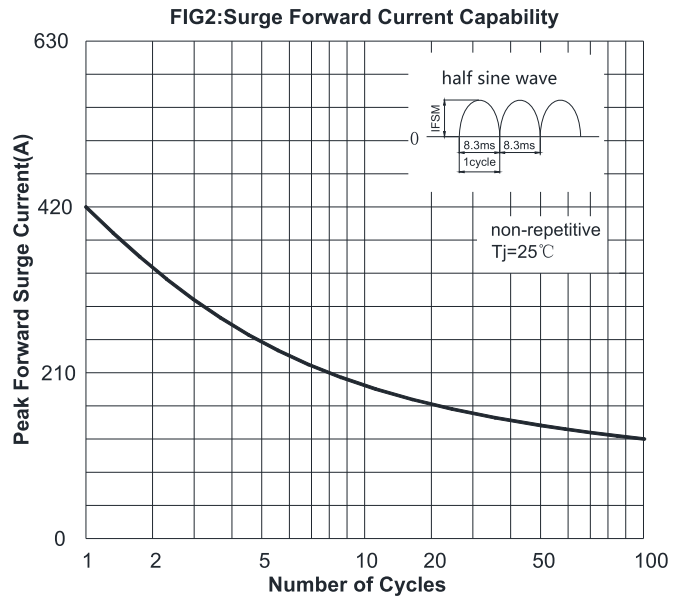
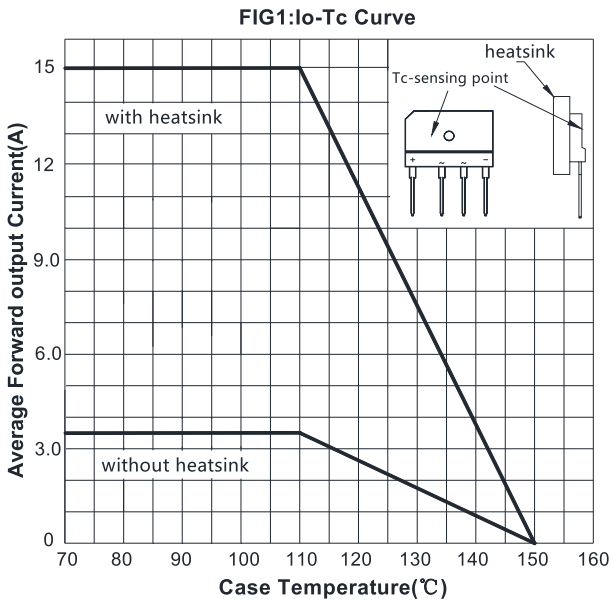
PARAMETER		SYMBOL	UNIT	GBJ1508A
Typical Thermal Resistance	Between junction and ambient, Without heatsink	$R_{\theta J-A}$	$^{\circ}\text{C/W}$	18.0
	Between junction and case, With heatsink	$R_{\theta J-C}$		1.5

Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

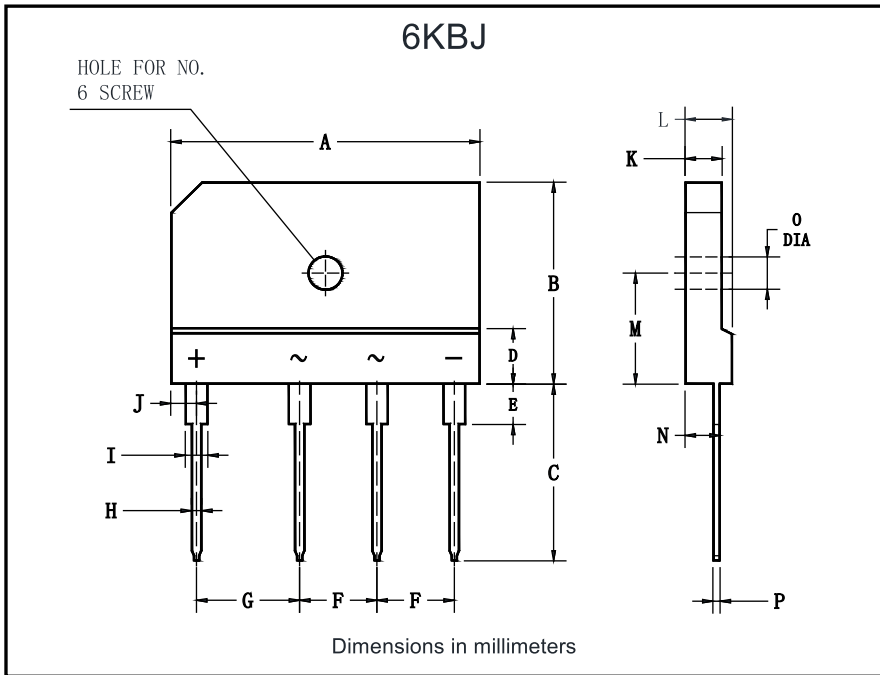
■ **PACKAGING INFORMATION**

PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GBJ1508A	B1	Approximate 6.5	15	750	1500	TUBE

■ **CHARACTERISTICS (TYPICAL)**



■ **OUTLINE DIMENSIONS**



6KBJ		
Dim	Min	Max
A	29.7	30.3
B	19.7	20.3
C	17.0	18.0
D	4.8	5.8
E	3.8	4.2
F	7.3	7.7
G	9.8	10.2
H	0.9	1.1
I	2.0	2.4
J	2.3	2.7
K	3.4	3.8
L	4.4	4.8
M	10.8	11.2
N	3.1	3.7
O	3.1	3.4
P	0.6	0.8